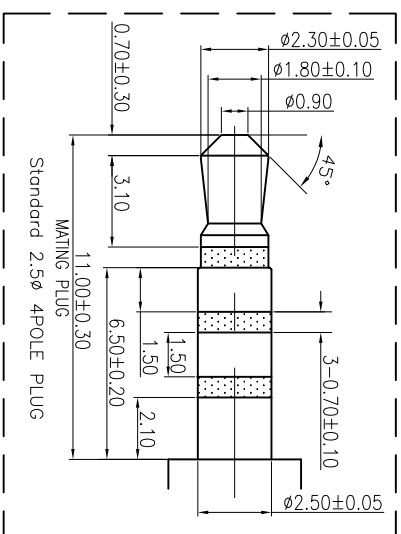
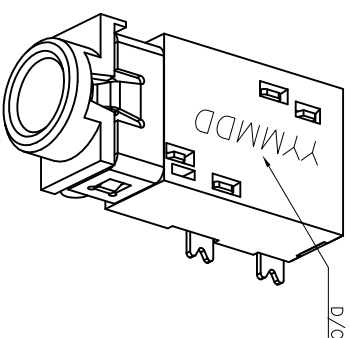
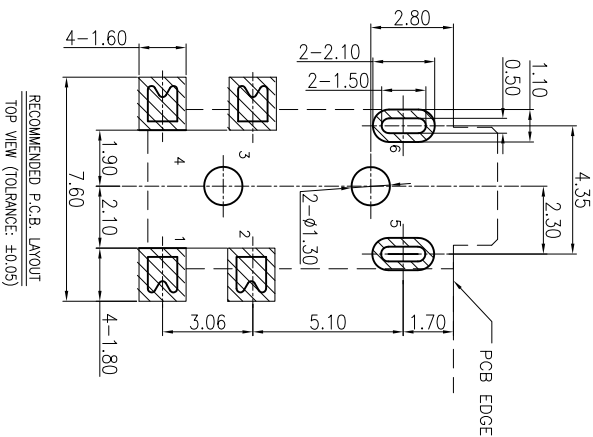


- NOTE:
1. SPECIFICATIONS SEE THE 2.5&3.5 PHONE JACK SPECIFICATIONS
  2. SOLDER HEAT RESISTANCE: IR REFLOW CONDITION 260°C 10 SECS.
  3. TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
  4. GREEN PRODUCT IDENTIFICATION MARK IN JACK: "G.P. PASS"
  5. GREEN PRODUCT IDENTIFICATION LABEL IN PACKING:
  6. FOR SOLDERING LEAD-FREE PROCESS.
  7. MATING FORCE 3kg Max. UNMATING FORCE 0.3kg Min.
  8. WORKING VOLTAGE : 36V MAX.
  9. D/C DESCRIPTION

YY MM DD  
DAY  
MONTH  
YEAR

RECOMMENDED PCB LAYOUT  
TOP VIEW (TOLERANCE: ±0.05)



B

8	COVER	1	SUS 0.15t		
7	SHUNT-B	1	BRASS 0.2T	Au 3u" Min.	
6	SHUNT-A	1	BRASS 0.2T	Au 3u" Min.	
5	RING SPRING-B	1	COPPER ALLOY 0.2t	GOLD FLASH	
4	RING SPRING-A	1	COPPER ALLOY 0.2t	GOLD FLASH	
3	TIP SPRING	1	COPPER ALLOY 0.2t	Au 3u" Min.	
2	EARTH SPRING	1	COPPER ALLOY 0.2t	Au 3u" Min.	
1	BODY	1	HIGH TEMP. THERMOPLASTIC	BLACK COLOR	

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singotron Enterprise Co., Ltd.  
信譽電子(中山)有限公司

DECIMALS:	ANGLES:	TITLE	PART NO.
X :±0.5	X :±2	2.5ØPHONEJACK	25J2268-002111
X.X :±0.3	X.X :±1		
X.XX :±0.2			

CHKD	SCALE	UNIT	REV.
ZJZ	1:1	mm	B
APVD	SIZE	SHEET	
14/4/21	A3	10F1	

CUSTOMER COPY

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASED	CHARLIE	06/06/07
B	ECN NO.:C140027 UPDATE PLATING	ZJLS	2014.4.15